

ABSTRACT

A solid or semi-solid thermoplastic adhesive adhered to a surface mount electronic device; an assembly made of at least a printed circuit board, a surface mount electronic device, solder joints providing a connection between the printed circuit board and the device, and solid thermoplastic adhesive joints attached to the device and the board. The thermoplastic adhesive is at least softened and applied to any available surface on the connecting substrate of the surface mounted electronic device. The thermoplastic adhesive is heated to a temperature sufficient to provide an adhesive joint between the organic surface and the board. There is also provided a thermoplastic adhesive composition having at least the following components:

(A) from 5% to 98% by weight of a functionalized polyolefin, and

(B) from 2% to 95% by weight of a polyamide compound.